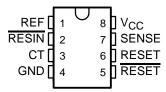
TL7702A, TL7705A, TL7709A, TL7712A, TL7715A SUPPLY-VOLTAGE SUPERVISORS

SLVS028H - APRIL 1983 - REVISED MAY 2003

- Power-On Reset Generator
- Automatic Reset Generation After Voltage Drop
- Wide Supply-Voltage Range
- Precision Voltage Sensor
- Temperature-Compensated Voltage Reference
- True and Complement Reset Outputs
- Externally Adjustable Pulse Duration

description/ordering information

TL7702A, TL7709A, TL7712A, TL7715A . . . D OR P PACKAGE TL7705A . . . D, P, OR PS PACKAGE, (TOP VIEW)



ORDERING INFORMATION

TA	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP (P)	Tube of 50	TL7702ACP	TL7702ACP
	COIC (D)	Tube of 75	TL7702ACD	770040
	SOIC (D)	Reel of 2500	TL7702ACDR	7702AC
	PDIP (P)	Tube of 50	TL7705ACP	TL7705ACP
	SOIC (D)	Tube of 75	TL7705ACD	7705AC
	SOIC (D)	Reel of 2500	TL7705ACDR	7705AC
	SOP (PS)	Reel of 2000	TL7705ACPSR	T7705A
0°C to 70°C	PDIP (P)	Tube of 50	TL7709ACP	TL7709ACP
	SOIC (D)	Tube of 75	TL7709ACD	7709AC
	SOIC (D)	Reel of 2500	TL7709ACDR	7709AC
	PDIP (P)	Tube of 50	TL7712ACP	TL7709ACP
	SOIC (D)	Tube of 75	TL7712ACD	7712AC
		Reel of 2500	TL7712ACDR	7712AC
	PDIP (P)	Tube of 50	TL7715ACP	TL7715ACP
	SOIC (D)	Tube of 75	TL7715ACD	7715AC
	PDIP (P)	Tube of 50	TL7702AIP	TL7702AIP
-40°C to 85°C	SOIC (D)	Tube of 75	TL7702AID	7702AI
	SOIC (D)	Reel of 2500	TL7702AIDR	7702AI
	PDIP (P)	Tube of 50	TL7705AIP	TL7705AIP
	SOIC (D)	Tube of 75	TL7705AID	7705AI
	SOIC (D)	Reel of 2500	TL7705AIDR	IACUTT

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



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description/ordering information (continued)

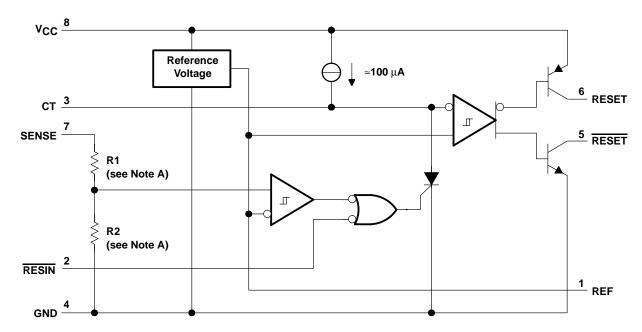
The TL77xxA family of integrated-circuit supply-voltage supervisors is designed specifically for use as reset controllers in microcomputer and microprocessor systems. The supply-voltage supervisor monitors the supply for undervoltage conditions at the SENSE input. During power up, the \overline{RESET} output becomes active (low) when V_{CC} attains a value approaching 3.6 V. At this point (assuming that SENSE is above V_{IT+}), the delay timer function activates a time delay, after which outputs \overline{RESET} and \overline{RESET} go inactive (high and low, respectively). When an undervoltage condition occurs during normal operation, \overline{RESET} and \overline{RESET} go active. To ensure that a complete reset occurs, the reset outputs remain active for a time delay after the voltage at the SENSE input exceeds the positive-going threshold value. The time delay is determined by the value of the external capacitor C_T : $t_d = 1.3 \times 10^4 \times C_T$, where C_T is in farads (F) and t_d is in seconds (s).

During power down and when SENSE is below V_{IT-} , the outputs remain active until V_{CC} falls below 2 V. After this, the outputs are undefined.

An external capacitor (typically 0.1 μ F) must be connected to REF to reduce the influence of fast transients in the supply voltage.

functional block diagram

The functional block diagram is shown for illustrative purposes only; the actual circuit includes a trimming network to adjust the reference voltage and sense-comparator trip point.



NOTES: A. TL7702A: R1 = 0 Ω , R2 = open

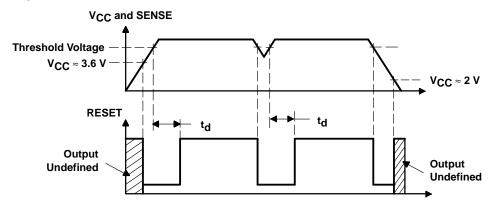
TL7705A: R1 = 7.8 k Ω , R2 = 10 k Ω TL7709A: R1 = 19.7 k Ω , R2 = 10 k Ω TL7712A: R1 = 32.7 k Ω , R2 = 10 k Ω

TL7715A: R1 = 43.4 k Ω , R2 = 10 k Ω

B. Resistor values shown are nominal.



timing diagram



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC} (see Note 1)	20 V
Input voltage range, V _I , RESIN	
Input voltage range, V _I , SENSE:TL7702A (see Note 2)	
TL7705A	0.3 V to 20 V
TL7709A	0.3 V to 20 V
TL7712A, TL7715A	0.3 V to 20 V
High-level output current, IOH, RESET	–30 mA
Low-level output current, IOL, RESET	30 mA
Package thermal impedance, θ_{JA} (see Notes 3 and 4): D package	97°C/W
P package	85°C/W
PS package	95°C/W
Operating virtual junction temperature, T _J	150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values are with respect to GND.
 - 2. For proper operation of the TL7702A, the voltage applied to the SENSE terminal should not exceed V_{CC} 1 V or 6 V, whichever is less.
 - 3. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - 4. The package thermal impedance is calculated in accordance with JESD 51-7.



TL7702A, TL7705A, TL7709A, TL7712A, TL7715A SUPPLY-VOLTAGE SUPERVISORS

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recommended operating conditions

			MIN	MAX	UNIT
VCC	Supply voltage	3.5	18	V	
VIH	High-level input voltage at RESIN	2		V	
V _{IL}	Low-level input voltage at RESIN			0.6	V
VI		TL7702A	0	See Note 2	
		TL7705A	0	10	
	Input voltage, SENSE	TL7709A	0	15	V
		TL7712A	0	20	
		TL7715A	0	20	
loh	High-level output current, RESET	•		-16	mA
l _{OL}	Low-level output current, RESET			16	mA
т.	On another from all terms and the		0	70	°C
T _A	Operating free-air temperature range TL77xxA			85	30

NOTE 2: For proper operation of the TL7702A, the voltage applied to the SENSE terminal should not exceed $V_{CC}-1\ V$ or 6 V, whichever is less.

electrical characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER			TEST CONDITIONS†		TL77xxAC TL77xxAI				
					MIN	TYP	MAX		
VOH High-level output voltage, RESET				I _{OH} = -16 mA	V _{CC} -1.5			V	
VOL	Low-level output voltage, RE	SET		I _{OL} = 16 mA			0.4	V	
V _{ref}	Reference voltage			T _A = 25°C	2.48	2.53	2.58	V	
			TL7702A		2.48	2.53	2.58		
			TL7705A		4.5	4.55	4.6		
VIT-	VIT- Negative-going input threshold SENSE	ld voltage,	TL7709A	T _A = 25°C	7.5	7.6	7.7	V	
			TL7712A	1	10.6	10.8	11		
			TL7715A		13.2	13.5	13.8		
	TL		TL7702A			10			
		Ī	TL7705A	T _A = 25°C		15 20		mV	
V _{hys}	Hysteresis, SENSE (VIT+ - V	/IT_)	TL7709A						
			TL7712A		35				
			TL7715A		45]	
				$V_I = 2.4 \text{ V to V}_{CC}$			20		
Ц	Input current	RESIN	_	V _I = 0.4 V	-		-100	μΑ	
	S		TL7702A	$V_{ref} < V_{I} < V_{CC} - 1.5 V$	0.5 2				
IOH High-level output current, RESET			V _O = 18 V			50	μΑ		
			V _O = 0			-50	μΑ		
ICC	Supply current			All inputs and outputs open		1.8	3	mA	

 $^{^\}dagger$ All electrical characteristics are measured with 0.1- μ F capacitors connected at REF, CT, and V_{CC} to GND.



switching characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER			TEST CON	TL77xxAC TL77xxAI			UNIT	
			MIN	TYP	MAX			
	Output pulse duration		$C_T = 0.1 \mu F$		0.65	1.2	2.6	msec
Input pulse duration at RESIN				0.4			μs	
tw(S)	Pulse duration at SENSE input to switch outputs		$V_{IH} = V_{IT-} + 200 \text{ mV},$	V _{IL} = V _{IT} – 200 mV	2			μs
t _{pd}	t _{pd} Propagation delay time, RESIN to RESET		V _{CC} = 5 V				1	μs
	Rise time	RESET	V 5 V	See Note 5			0.2	
t _r	Rise time	RESET	V _{CC} = 5 V,	See Note 5			3.5	μS
t. Fall time		RESET	V 5 V	Coo Noto E			3.5	
tf	Fall time VCC		$A \cap A \subset C = 2 \text{ A}$	$V_{CC} = 5 \text{ V},$ See Note 5			0.2	μS

[†] All switching characteristics are measured with 0.1- μ F capacitors connected at REF and $\underline{V_{CC}}$ to GND. NOTE 5: The rise and fall times are measured with a 4.7- $k\Omega$ load resistor at RESET and RESET.

PARAMETER MEASUREMENT INFORMATION

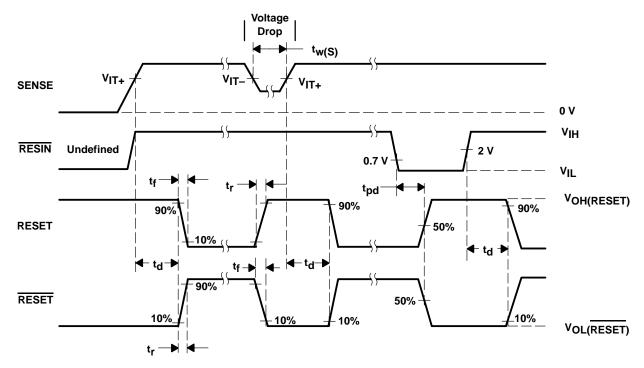
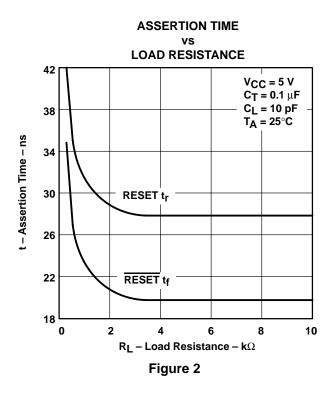
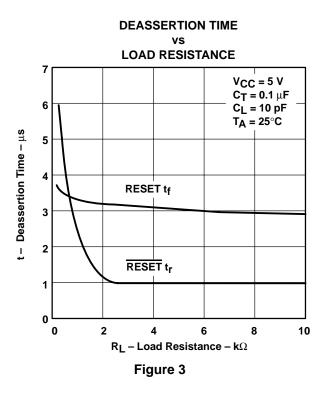
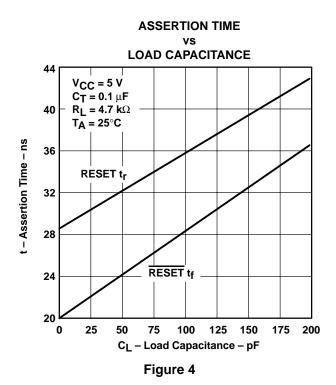


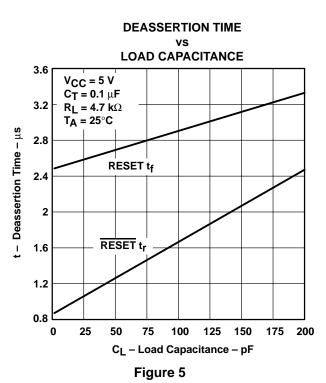
Figure 1. Voltage Waveforms

TYPICAL CHARACTERISTICS[†]









[†] For proper operation, both RESET and RESET should be terminated with resistors of similar value. Failure to do so may cause unwanted plateauing in either output waveform during switching.



APPLICATION INFORMATION

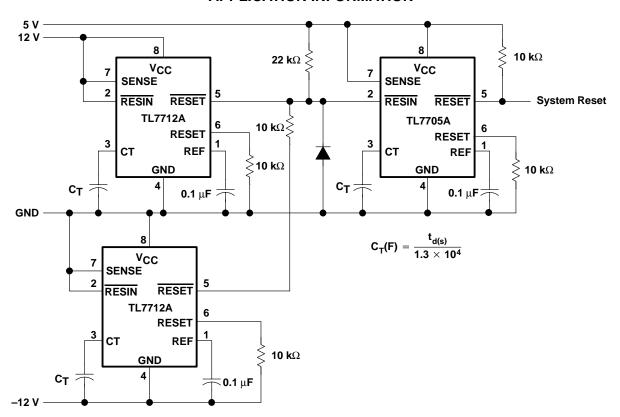


Figure 6. Multiple Power-Supply System Reset Generation

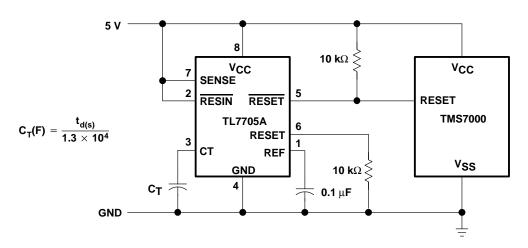


Figure 7. Reset Controller for TMS7000 System

APPLICATION INFORMATION

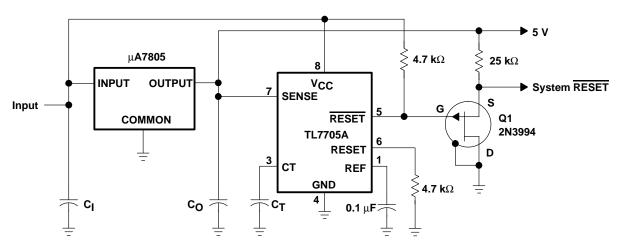


Figure 8. Eliminating Undefined States Using a P-Channel JFET

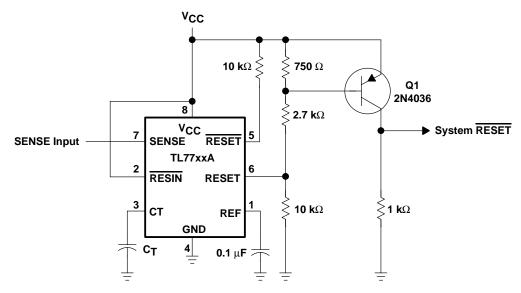


Figure 9. Eliminating Undefined States Using a pnp Transistor



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-88685012A	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
TL7702ACD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7702ACDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7702ACDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7702ACDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7702ACDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7702ACDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7702ACP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL7702ACPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL7702AID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7702AIDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7702AIDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7702AIDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7702AIDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7702AIDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7702AIP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL7702AIPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL7702AMFKB	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
TL7702AMJG	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
TL7702AMJGB	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
TL7705ACD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7705ACDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7705ACDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7705ACDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7705ACDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7705ACDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7705ACP	ACTIVE	PDIP	P	8	50	Pb-Free	CU NIPDAU	N / A for Pkg Type





om 31-Oct-2006

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
						(RoHS)		
TL7705ACPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL7705ACPSLE	OBSOLETE	SO	PS	8		TBD	Call TI	Call TI
TL7705ACPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7705ACPSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7705AID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7705AIDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7705AIDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7705AIDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7705AIDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7705AIDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7705AIP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL7705AIPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL7705AMFKB	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
TL7705AMJG	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
TL7705AMJGB	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
TL7709ACD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
TL7709ACDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
TL7709ACDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
TL7709ACDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
TL7709ACP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL7709ACPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL7709AID	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI
TL7709AIP	OBSOLETE	PDIP	Р	8		TBD	Call TI	Call TI
TL7712ACD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
TL7712ACDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
TL7712ACDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
TL7712ACDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
TL7712ACP	ACTIVE	PDIP	Р	8	50	Pb-Free	CU NIPDAU	N / A for Pkg Type





.com 31-Oct-2006

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
						(RoHS)		
TL7712ACPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL7712AID	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI
TL7712AIP	OBSOLETE	PDIP	Р	8		TBD	Call TI	Call TI
TL7715ACD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7715ACDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL7715ACP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL7715ACPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL7715AID	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI
TL7715AIP	OBSOLETE	PDIP	Р	8		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

JG (R-GDIP-T8)

CERAMIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP1-T8

FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001

For the latest package information, go to $http://www.ti.com/sc/docs/package/pkg_info.htm$

D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AA.





NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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